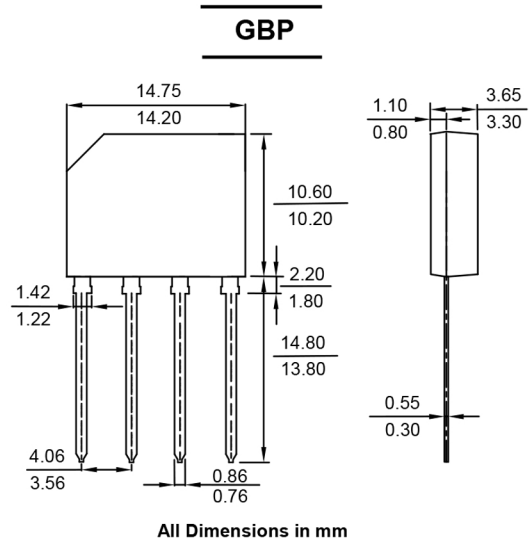


## Features

- Diffused Junction
- Low Forward Voltage Drop
- High Current Capability
- High Reliability
- High Surge Current Capability
- Ideal for Printed Circuit Boards

## Mechanical Data

- Case: Molded Plastic
- Terminals: Plated Leads Solderable per MIL-STD-202, Method 208
- Polarity: As Marked on Body
- Weight: 1.35 grams (approx.)
- Mounting Position: Any
- Marking: Type Number
- **Lead Free: For RoHS / Lead Free Version**



## Maximum Ratings and Electrical Characteristics @ $T_A=25^{\circ}\text{C}$ unless otherwise specified

Single Phase, half wave, 60Hz, resistive or inductive load.  
For capacitive load, derate current by 20%.

| Characteristic  | Symbol             | GBP 6005    | GBP 601 | GBP 602 | GBP 604 | GBP 606 | GBP 608 | GBP 610 | Unit               |
|---|--------------------|-------------|---------|---------|---------|---------|---------|---------|--------------------|
| Peak Repetitive Reverse Voltage<br>Working Peak Reverse Voltage<br>DC Blocking Voltage                                | VRRM<br>VRWM<br>VR | 50          | 100     | 200     | 400     | 600     | 800     | 1000    | V                  |
| RMS Reverse Voltage   | VR(RMS)            | 35          | 70      | 140     | 280     | 420     | 560     | 700     | V                  |
| Average Rectified Output Current<br>(Note 1) @ $T_A = 50^{\circ}\text{C}$   | $I_o$              | 6.0         |         |         |         |         |         |         | A                  |
| Non-Repetitive Peak Forward Surge Current<br>8.3ms Single half sine-wave superimposed on<br>rated load (JEDEC Method) | IFSM               | 150         |         |         |         |         |         |         | A                  |
| Forward Voltage (per element) @ $I_F = 6.0\text{A}$   | VFM                | 1.1         |         |         |         |         |         |         | V                  |
| Peak Reverse Current @ $T_A = 25^{\circ}\text{C}$<br>At Rated DC Blocking Voltage @ $T_A = 100^{\circ}\text{C}$       | IRM                | 10<br>500   |         |         |         |         |         |         | $\mu\text{A}$      |
| Typical Thermal Resistance (Note 3)   | $R_{\theta JA}$    | 40          |         |         |         |         |         |         | K/W                |
| Operating and Storage Temperature Range   | $T_J, T_{STG}$     | -55 to +150 |         |         |         |         |         |         | $^{\circ}\text{C}$ |

- Note: 1. Leads maintained at ambient temperature at a distance of 9.5mm from the case.  
2. Measured at 1.0 MHz and applied reverse voltage of 4.0V D.C.  
3. Thermal resistance junction to ambient mounted on PC board with 12mm<sup>2</sup> copper pad.

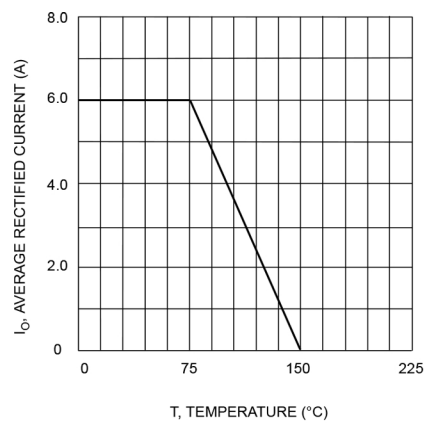


Fig. 1 Forward Current Derating Curve

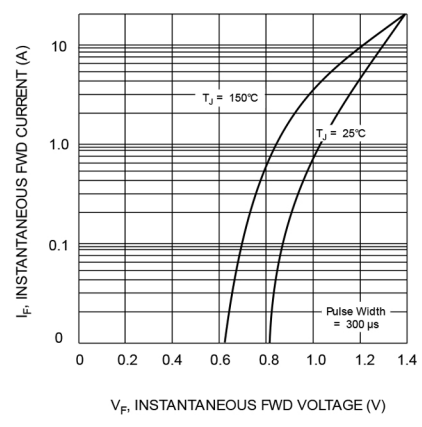


Fig. 2 Typical Fwd Characteristics

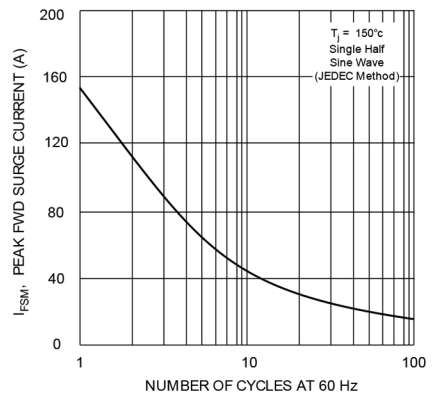


Fig. 3 Max Non-Repetitive Peak Fwd Surge Current

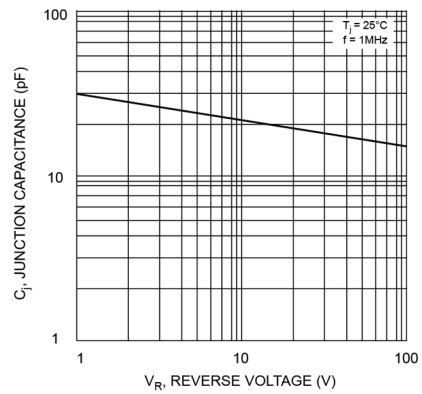


Fig. 4 Typical Junction Capacitance

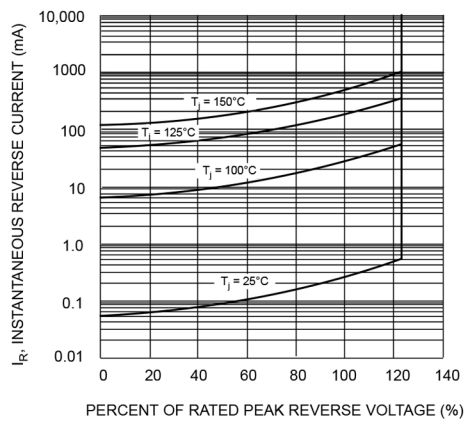


Fig. 5 Typical Reverse Characteristics

单击下面可查看定价，库存，交付和生命周期等信息

[>>RCD\(达标电子\)](#)